

Silicon N-Channel Planar Power MOSFET

Description

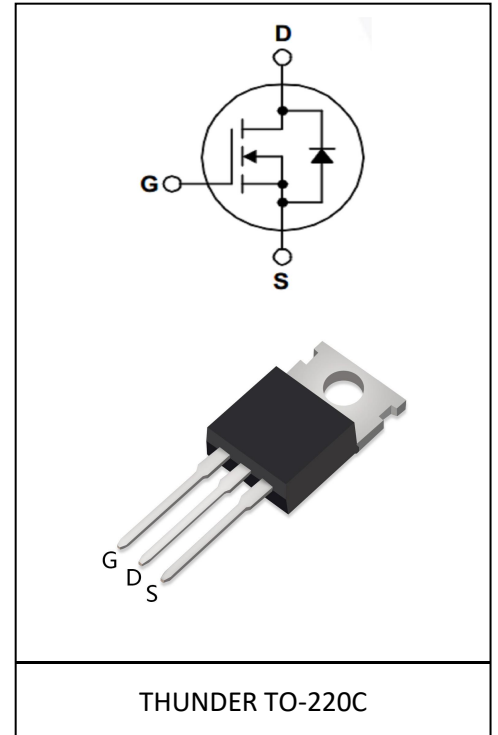
The TH40N20PC utilizes the latest processing techniques to achieve low on-resistance per silicon area. Additional features of this MOSFET are 150°C operating junction temperature and high repetitive peak current capability. These features combine to make this MOSFET a highly efficient, robust and reliable device for PDP driving applications. It can be used in a wide variety of applications.

General Features

- $V_{DS}=200V, I_D=40A$
- Low ON Resistance, $R_{DS(ON)}=60m\Omega @ V_{GS}=10V, I_D=20A$
- Low reverse transfer capacitance
- Low Qg for fast response
- Short fall & rise times for fast switching
- 100% single pulse avalanche energy Test

Application

- Power switching application
- Digital amplifier
- Adapter and charger



Product Summary

V_{DS}	200V
$R_{DS(on)}$	60m Ω
I_D	40A

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	200	V
Continuous drain current $T_C = 25^\circ C$ (Silicon limit)	I_D	40	A
Pulsed drain current ($T_C = 25^\circ C$, t_p limited by T_{jmax})	I_{DM}	160	A
Avalanche energy, single pulse ($L=10mH$, $R_g=25\Omega$)	E_{AS}	516	mJ
Gate-Source voltage	V_{GS}	± 30	V
Power dissipation ($T_C = 25^\circ C$)	P_D	290	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+150	$^\circ C$

Thermal Resistance

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case.	R_{thJC}	0.43	°C/W
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	62.5	

Electrical Characteristic (at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	200	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{GS(th)}$	2.0	-	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=200V, V_{GS}=0V$ $T_j=25\text{ }^\circ\text{C}$
		-	-	10	μA	$V_{DS}=160V, V_{GS}=0V$ $T_j=125\text{ }^\circ\text{C}$
Gate-source leakage current	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 30V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	60	72	m Ω	$V_{GS}=10V, I_D=20A$
Transconductance	g_{fs}	-	28.5	-	S	$V_{DS}=40V, I_D=20A$

Dynamic Characteristic

Input Capacitance	C_{iss}	-	3090	-	pF	$V_{GS}=0V, V_{DS}=25V,$ $f=1\text{MHz}$
Output Capacitance	C_{oss}	-	305	-		
Reverse Transfer Capacitance	C_{rss}	-	2.5	-		
Gate Total Charge	Q_g	-	39	-	nC	$V_{GS}=10V, V_{DS}=160V,$ $I_D=40A$
Gate-Source charge	Q_{gs}	-	10	-		
Gate-Drain charge	Q_{gd}	-	17.5	-		
Turn-on delay time	$t_{d(on)}$	-	32	-	ns	$V_{DD}=100V, I_D=40A,$ $R_G=25\Omega$
Rise time	t_r	-	168	-		
Turn-off delay time	$t_{d(off)}$	-	145	-		
Fall time	t_f	-	145	-		
Gate resistance	R_G	-	0.9	-	Ω	$V_{GS}=0V, V_{DS}=0V,$ $f=1\text{MHz}$

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	-	1.4	V	$V_{GS}=0V, I_{DS}=40A$
Body Diode Continuous Forward Current	I_S	-	-	40	A	$T_C=25^\circ C$
Body Diode Reverse Recovery Time	t_{rr}	-	155	-	ns	$T_C=25^\circ C, I_S=40A,$ $di/dt=100A/us$
Body Diode Reverse Recovery Charge	Q_{rr}	-	1.3	-	μC	

Typical Performance Characteristics

Fig 1: On-Region Characteristics

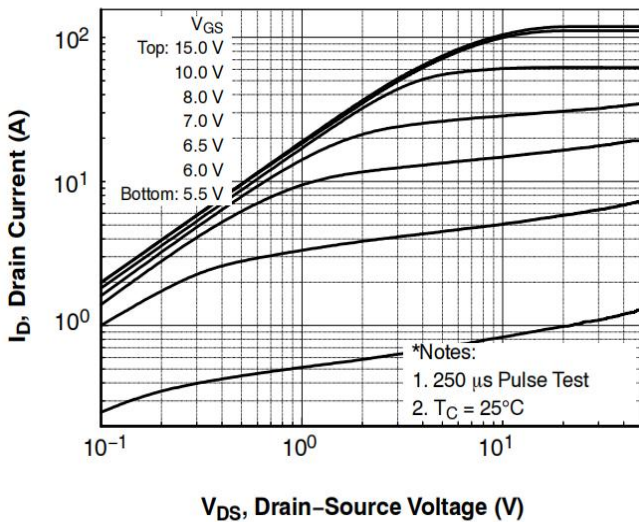


Fig 2: Transfer Characteristics

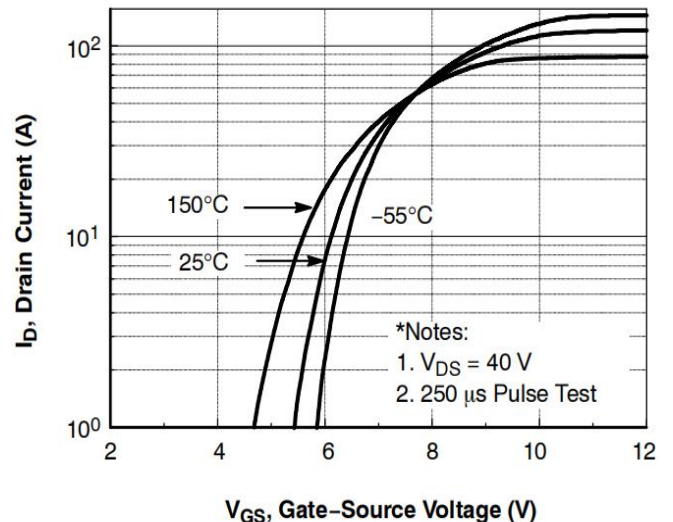


Fig 3: On-Resistance Variation vs. Drain Current and Gate Voltage

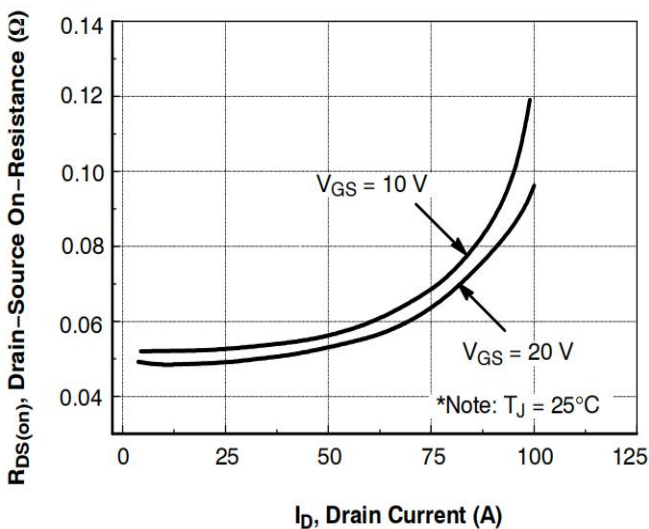


Fig 4: On-Resistance Variation vs. Temperature

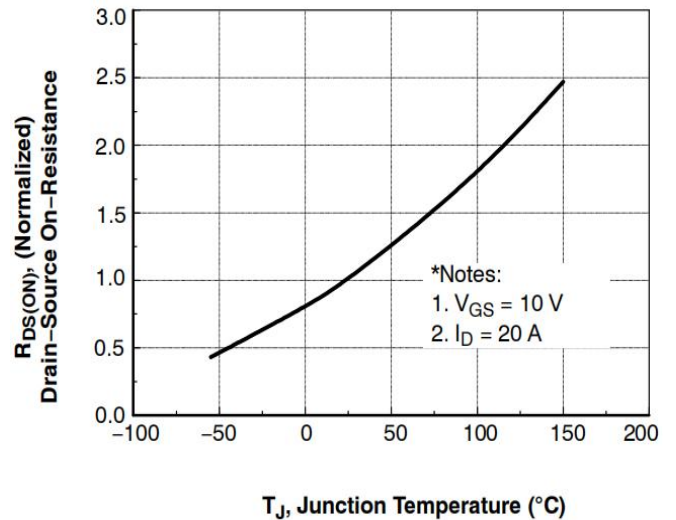


Fig 5: Gate Charge Characteristics

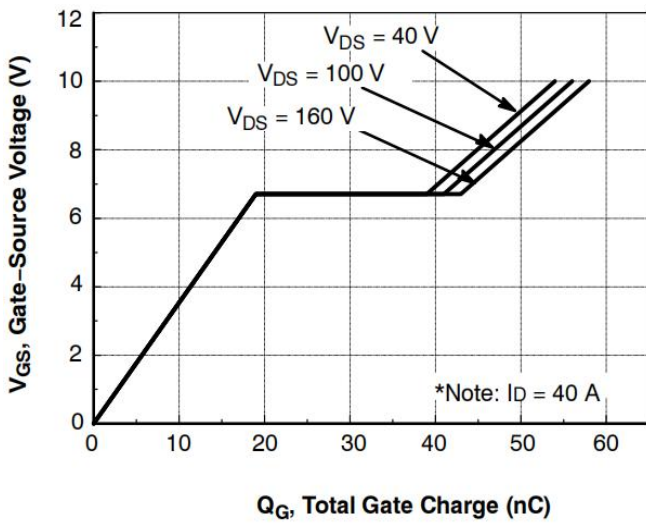


Fig 6: Capacitance Characteristics

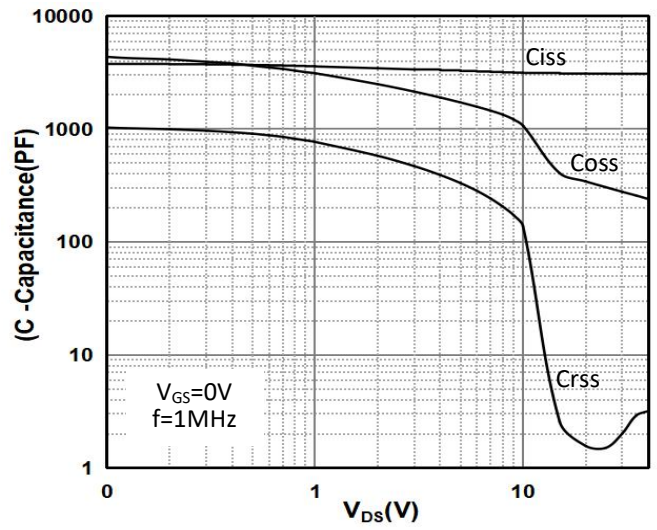


Fig 7: Power Dissipation

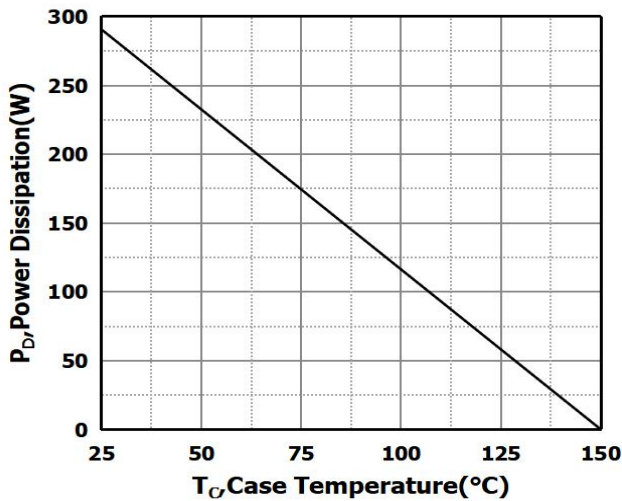


Fig 8: Drain Current Derating

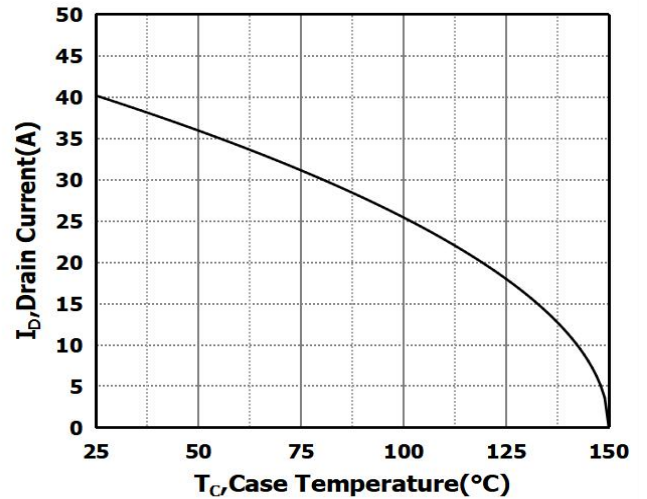


Fig 9: Body Diode Forward Voltage Variation vs. Source Current and Temperature

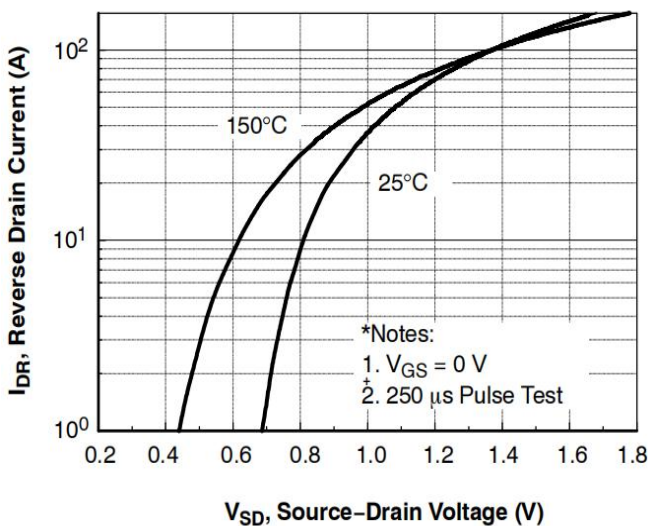


Fig 10: Safe Operating Area

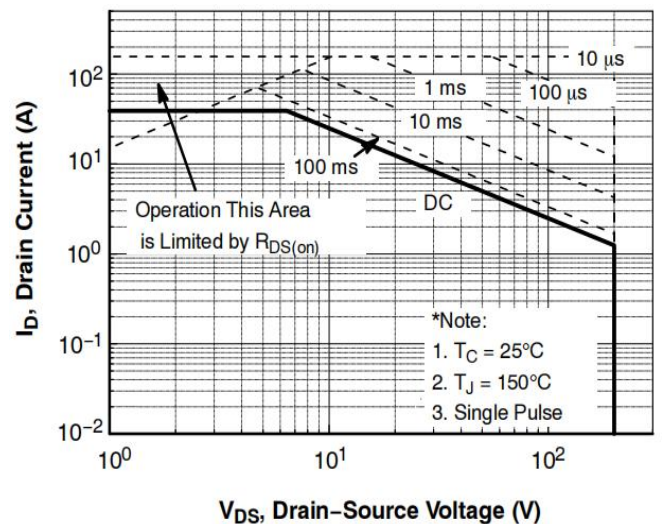
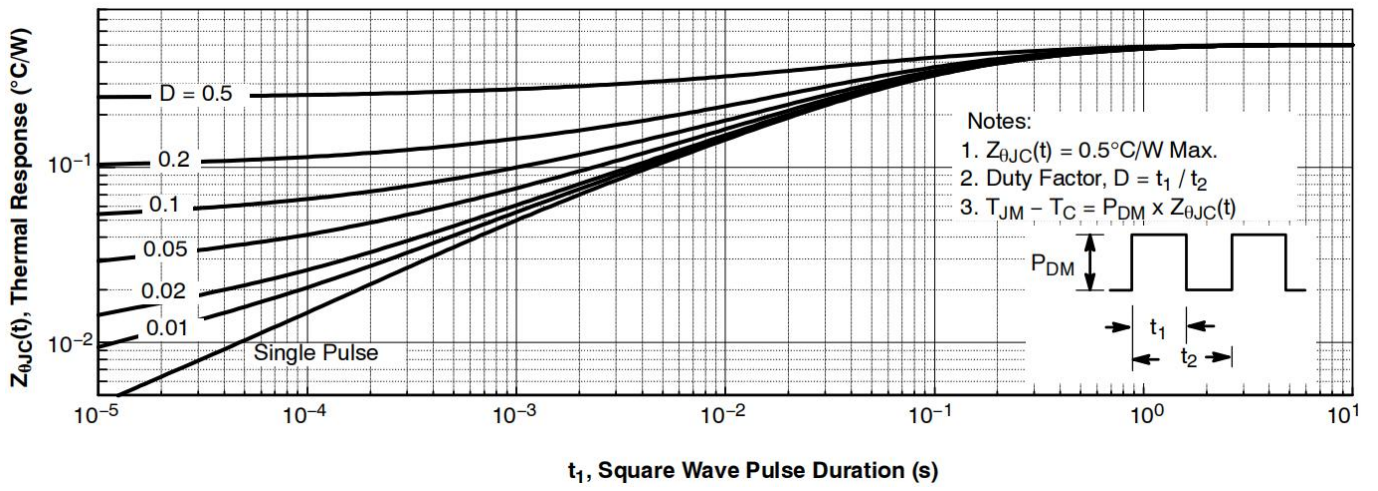
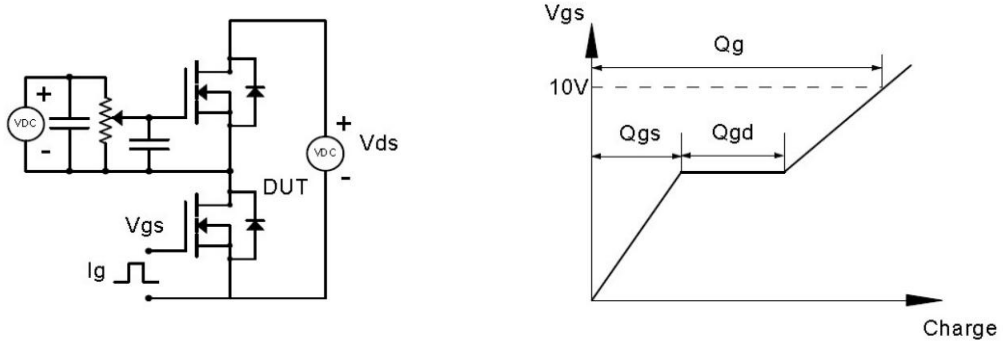


Fig 11: Transient Thermal Response Curve

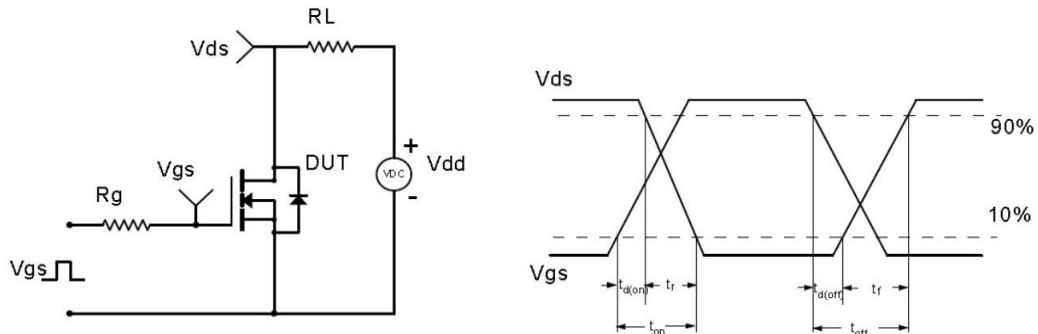


Test Circuit & Waveform

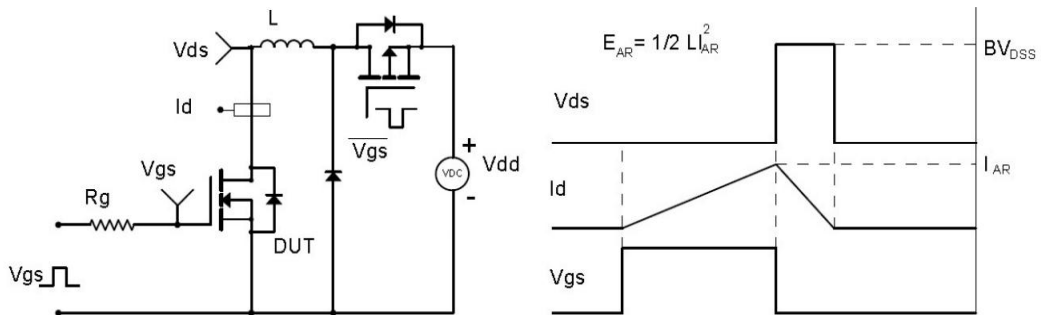
Gate Charge Test Circuit & Waveform



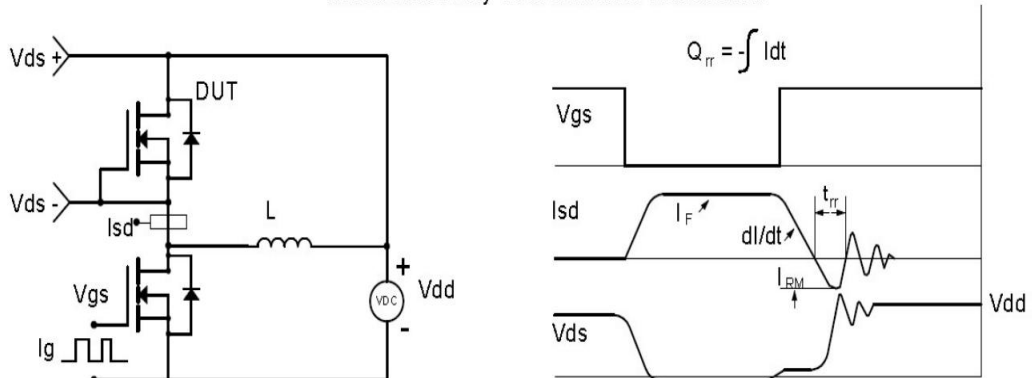
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

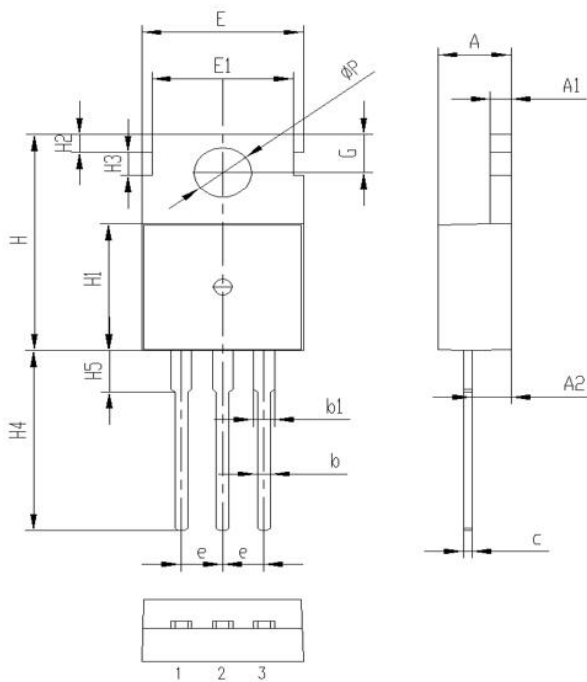


Package Information

Package Information

TO-220C PACKAGE

基本尺寸



Symbol	单位 mm		
	Min	Nom	Max
A	4.30	4.5	4.70
A1	1.20	1.30	1.40
A2	2.20	2.4	2.60
b	0.60	0.8	1.00
b1	1.20	1.30	1.40
c	0.40	0.5	0.60
e	2.44	2.54	2.64
E	9.80	10.0	10.2
E1	8.50	8.70	8.90
H	15.5	15.7	15.9
H1	9.00	9.2	9.40
H2	1.10	1.34	1.50
H3	1.50	1.7	1.90
H4	12.9	13.3	13.7
H5	2.80	3.0	3.20
G	2.60	2.8	3.00
ΦP	3.40	3.6	3.80

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